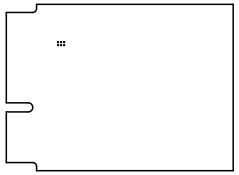
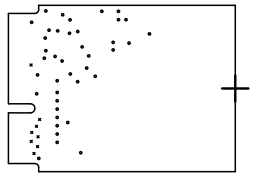


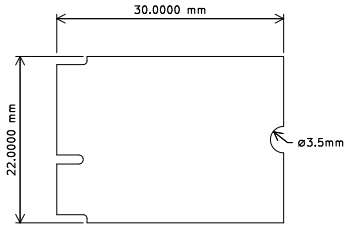
Drill Map:

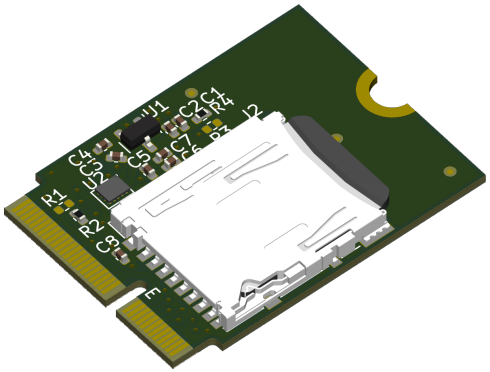
· 0.102mm / 0.0040" (6 holes)



Drill Map:

· 0.254mm / 0.0100" (8 holes)
· 0.300mm / 0.0118" (40 holes)
+ 3.500mm / 0.1378" (1 hole)




## BOARD CHARACTERISTICS

| | | | |
|---|---|---|---|
| Copper Layer Count: | 4 | Board Thickness: | 0.7800 mm |
| Board overall dimensions: | 30.0000 mm x 22.0000 mm | | |
| Min track/spacing: | 0.1270 mm / 0.1270 mm | Min hole diameter: | 0.2540 mm |
| Copper Finish: | ENIG | Impedance Control: | No |
| Castellated pads: | No | Plated Board Edge: | No |
| Edge card connectors: | Yes | | |

| Layer Name | Type | Material | Thickness (mm) | Color | Epsilon R | Loss Tangent |
|---|---|---|---|---|---|---|
| F.Silkscreen | Top Silk Screen | Liquid Photo | 0 mm | White | 1 | 0 |
| F.Paste | Top Solder Paste | | 0 mm | | 1 | 0 |
| F.Mask | Top Solder Mask | Epoxy | 0.01 mm | Green | 3.3 | 0 |
| F.Cu | copper | | 0.035 mm | | 1 | 0 |
| Dielectric | prepreg | PP2116 | 0.11 mm | FR4 natural | 4.29 | 0.02 |
| In1.Cu | copper | | 0.035 mm | | 1 | 0 |
| Dielectric | core | FR4 | 0.4 mm | FR4 natural | 4.29 | 0.02 |
| In2.Cu | copper | | 0.035 mm | | 1 | 0 |
| Dielectric | prepreg | PP2116 | 0.11 mm | FR4 natural | 4.29 | 0.02 |
| B.Cu | copper | | 0.035 mm | | 1 | 0 |
| B.Mask | Bottom Solder Mask | Epoxy | 0.01 mm | Green | 3.3 | 0 |
| B.Paste | Bottom Solder Paste | | 0 mm | | 1 | 0 |
| B.Silkscreen | Bottom Silk Screen | Liquid Photo | 0 mm | White | 1 | 0 |

**NOTE: UNLESS OTHERWISE SPECIFIED**

1. THIS BOARD SHALL CONFORM TO:
   IPC-6012, CURRENT REVISION, CLASS II
   IPC-A-600, CURRENT REVISION, CLASS II
2. OVERALL BOARD THICKNESS SHALL BE 0.80mm +/-10%.
3. MATERIAL SHALL BE IT180A OR EQUIVALENT.
4. SEE SUPPLEMENTARY PDF DOCUMENT FOR STACKUP COMPOSITION AND IMPEDANCE REQUIREMENTS.
5. USE SUPPLIED IPC-D-356 NETLIST TO PERFORM COMPARISON WITH GERBER DATA PRIOR TO MANUFACTURING.
6. APPLY SOLDERMASK OVER BARE COPPER, COLOR GREEN; MASK SHALL MEET IPC-SM-840.
7. SILKSCREEN SHALL BE WHITE NON-CONDUCTIVE INK, AND IS NOT PERMITTED ON ANY EXPOSED COPPER FEATURES.
8. SURFACE FINISH SHALL BE IMMERSION GOLD PER IPC 4552. COPPER FEATURES.
9. MINIMUM ANNULAR RING SHALL BE IN ACCORDANCE WITH IPC-6012 CLASS II.
10. ALL HOLES SHALL BE LOCATED WITHIN +/- 75 UM (0.003 INCH) OF TRUE POSITION.
11. ALL HOLES DIAMETERS INDICATED ARE FINISHED SIZE.
12. LAYER TO LAYER REGISTRATION SHALL BE +/- 75 UM (0.003 INCH).
13. COPPER FEATURES SHALL BE +/- 20% OF SUPPLIED DATA.
14. COPPER PLATING THICKNESS SHALL BE IN ACCORDANCE WITH IPC-6012 CLASS II.
15. WARP AND TWIST SHALL BE 0.75% IN ACCORDANCE WITH IPC-TM-650, #2.4.44
16. REMOVE ALL SHARP EDGES AND BURRS: 75 UM (0.003 INCH) MAXIMUM.
17. INSIDE RADIUS SHALL BE 0.06" MAXIMUM.
18. MICRO VIAS SHALL BE EPOXY FILLED AND OVERPLATED.
    SURFACE MUST BE PLANAR WITH .002" MAX. DIMPLE DEPTH ALLOWED.
    FILL REQUIREMENT AND COPPER THICKNESS PER IPC-6012 CLASS 2.
19. PCBS SHALL BE PANELIZED. VENDOR TO PROVIDE PANEL DRAWING FOR APPROVAL
    PRIOR TO STARTING MANUFACTURING



**Purism SPC**

Sheet:
File: m2-sd-card.kicad_pcb

***Title: M.2 SD Card***

| | | |
|---|---|---|
| Size: A4 | Date: 2023-05-11 | **Rev: v0.5.0** |
| KiCad E.D.A. kicad 7.0.2-1.fc38 | | Id: 1/1 |